As miniaturization trend for semiconductor chips continues, power density is increasing rapidly. So it has become very important, especially for high power semiconductors or high power lasers to remove the heat away from the chip efficiently and rapidly, to ensure a long life time for the chips. This webinar will focus on usage of high thermal conductivity materials as die attach and substrate materials for efficient heat removal.

Agenda:
- 16:00 - 16:05 : Welcome and Introduction
- 16:05 - 16:30 : "Advanced Thermal Management Solutions based on Diamond Composites", Dr. Erich Neubauer, Managing Director, RHP technology GmbH, Austria
- 16:30 - 16:55 : "Improving the Thermal Performance Through Silver Sintering in Power Electronics", Michiel de Monchy, Applications manager die attach and preforms Europe, Macdermid Alpha Assembly Solutions, The Netherlands
- 16:55 - 17:20 : "FEM modeling and experimental validation for advanced packaging and thermal management", Guido Spinola Durante, Expert, CSEM SA, Switzerland
- 17:20 - 17:30 : General discussions and closure

Please Join at 16:00 [CET], please mute your microphone.

**Date and Time**
- Date: 30 Sep 2021
- Time: 04:00 PM to 05:30 PM
- All times are Europe/Zurich
- Add Event to Calendar
  - iCal
  - Google Calendar

**Location**
Microsoft Teams meeting

**Join on your computer or mobile app**
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**Notice:** You can already join the meeting to validate it's working. Dear CSEM partner and customer, you don't need to have Teams to join this meeting. Click on the 'Join Teams Meeting' link to use the web application (WebApp).

**Hosts**
- Switzerland Section Chapter, EP21
- UK and Ireland Section Jt Chapter, RL07/EP21
- Germany Section Chapter, EP21
- Switzerland Section
- France Section, EP21

**Registration**
- Starts 19 July 2021 09:00 PM
- Ends 29 September 2021 09:00 PM
- All times are Europe/Zurich
• No Admission Charge